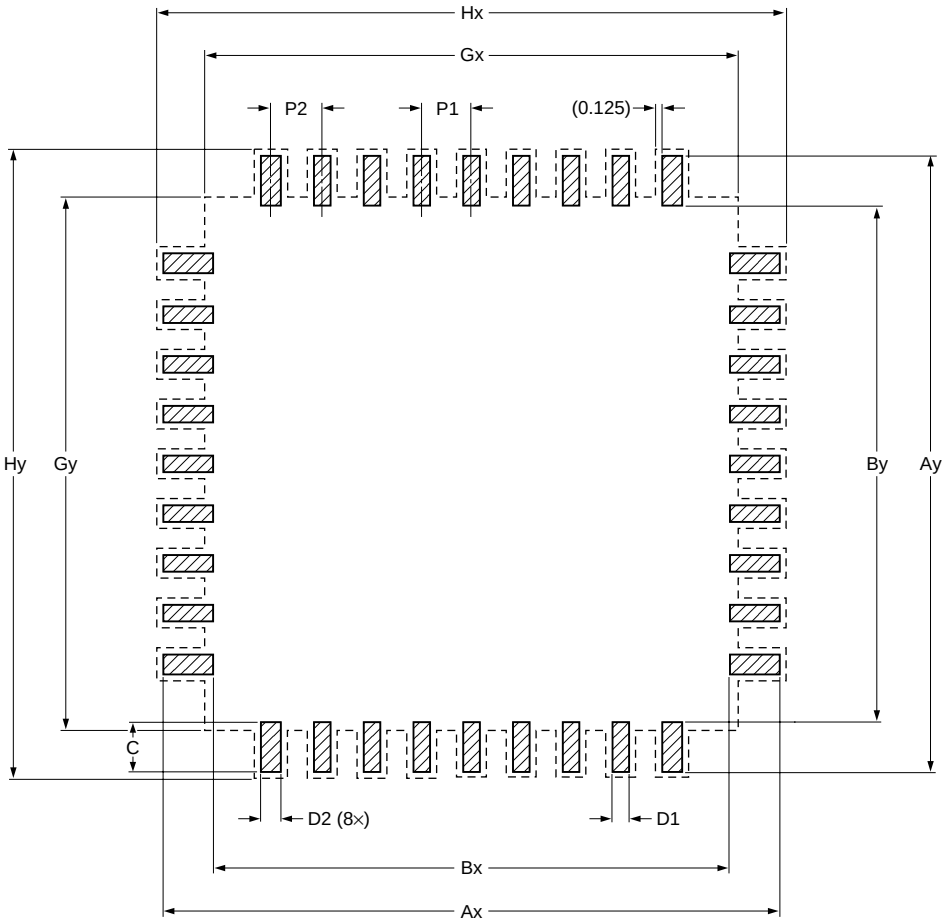
**Footprint information for reflow soldering of LQFP80 package** **SOT315-1**




Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

**DIMENSIONS in mm**

| P1 | P2 | Ax | Ay | Bx | By | C | D1 | D2 | Gx | Gy | Hx | Hy |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 0.500 | 0.560 | 15.300 | 15.300 | 12.300 | 12.300 | 1.500 | 0.280 | 0.400 | 12.500 | 12.500 | 15.550 | 15.550 |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